


MATERIAL DECLARATION SHEET



Material Number	CD0603-TxxC Series			
Product Line	Semiconductor Products			
Compliance Date	2007/9/28			
RoHS Compliant	YES	MSL	1	

No.	Construction Element (subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	FR-4 Board	Substrate/ Terminal	1.357	Copper	7440-50-8	29.34%	0.39814	41.45
				Nickel	7440-02-0	4.762%	0.06463	
				Gold	7440-57-5	0.155%	0.00210	
				Continuous Filament Fiber Glass	65997-17-3	65.74%	0.89213	
2	Wafer	Diode	0.029	Silicon	7440-21-3	97.948%	0.02840492	0.89
				Aluminum	7429-90-5	2%	0.00058	
				Titanium	7440-32-6	0.001%	0.00000029	
				Silver	7440-22-4	0.001%	0.00000029	
				Silicon dioxide	14808-60-7	0.05%	0.0000145	
3	Al wire	Conductor	0.001	Aluminum	7429-90-5	99.00%	0.00099	0.03
				Silicon	7440-21-3	1%	0.00001	
4	Silver paste	Welding	0.006	Modified Epoxy Resin	29690-82-2	16%	0.00096	0.18
				Silver	7440-22-4	80%	0.0048	
				Imidazole	827-43-0	2%	0.00012	
				Dicyandiamide	461-58-5	2%	0.00012	
5	Molding Compound	Outer	1.881	Silica	60676-86-0	80.00%	1.505	57.45
				Epoxy Resin	29690-82-2	10.00%	0.188	
				Phenolic Resin	9003-35-4	9.50%	0.179	
				Carbon Black	1333-86-4	0.50%	0.009	
		Total weight	3.274					

MATERIAL DECLARATION SHEET



This Document was updated on: 2015/11/30

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.